

IN THE CLAIMS

Claims 1-33 (Canceled).

34 (Previously Presented). A method of making a stencil which may be removably positioned over a semiconductor device for depositing material on the semiconductor before removing the stencil from over the device comprising:

forming a plurality of segmental annular openings in a stencil plate to define a central portion of the plate, a plurality of spokes, and a remainder of said stencil plate, said spokes connecting said central portion to the remainder of said plate between adjacent segmental annular openings; and

depositing material in said openings and under said central portion of said plate.

35 (Previously Presented). The method of claim 34 wherein forming a plurality of segmental annular openings in a stencil plate includes using a stencil plate having a thickness from about 3 to about 10 mils.

36 (Previously Presented). The method of claim 34 including forming said spokes to have a length of about 1 mil.

37 (Previously Presented). The method of claim 34 including forming said central portion in a circular shape.

38 (Previously Presented). The method of claim 34 including forming at least four openings and at least four spokes.

39 (Previously Presented). The method of claim 34 including maintaining a gap between said stencil and said device.